

### CLEAN VERSION OF AMENDED CLAIMS

1. An electronic chip component having all electrodes formed on one surface thereof, a side wall thereof being covered with a protective material, and wherein there is substantially no protective material located on the one surface of the chip where all the electrodes are formed and further wherein the protective material on the side wall and a surface of the chip opposite the surface where the electrodes are located have been grinded or polished to a common level .
2. The electronic chip component according to claim 1 wherein said protective material comprises either one of an organic insulating resin and an organic insulating material.
3. The electronic chip component according to claim 1, comprising a semiconductor chip diced at a position of said protective material for mounting on a packaging substrate, wherein all of said side wall is covered with said protective material.
4. The electronic chip component according to claim 3, wherein a solder bump is formed on each of said electrodes.
5. The electronic chip component according to claim 1, wherein a plurality of different types of semiconductor chips are bonded and integrated by said protective material.

6. A pseudo wafer comprising a plurality of same or different electronic chip components each having all electrodes formed on one surface thereof, bonded to each other with a protective material coated on side walls therebetween, and wherein there is no protective material located on the one surface of the chip where all the electrodes are formed and further wherein the protective material on the side wall and a surface of the chip opposite the surface where the electrodes are located have been grinded or polished to a common level ..

8. The pseudo wafer according to claim 6, wherein said pseudo wafer is diced into a single semiconductor chip at a position of said protective material for mounting on a packaging substrate.

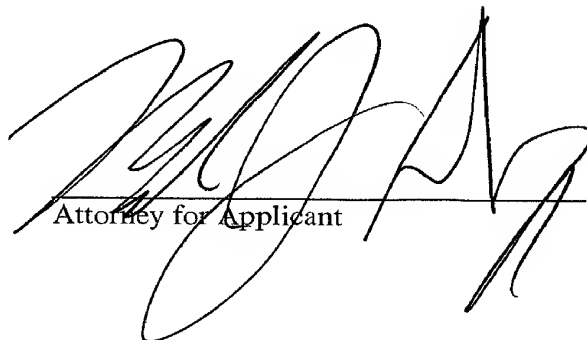
9. The pseudo wafer according to claim 8, wherein a solder bump is formed on each of said electrodes.



CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail on **December 30, 2002** in an envelope addressed to:

**Box ~~1~~ Fee Amendment  
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Attorney for Applicant

CHI1 #188506 v2